



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Representative Email *	Refer to Supplier Comment section		
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CBLT*UJ90ABA	A	ZY1A	2016-05-12
Amount	UoM	Unit type	ST ECOPACK Grade	
260.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	9x9x1	64	screw	
Comment	Package: LT VFQFPN2 9x9x1.0 64 PITCH 0.5; MDF valid for STHV748SQ			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CBLT*UJ90ABA					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	24.869	mg	supplier	die	Silicon (Si)	7440-21-3		24.363	mg	979653	93704
				supplier	metallization	Aluminium (Al)	7429-90-5		0.251	mg	10093	965
				supplier	Passivation	Silicon Oxide	7631-86-9		0.002	mg	80	8
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.253	mg	10174	973
Leadframe	Copper & its alloys	128.973	mg	supplier	alloy	Copper (Cu)	7440-50-8		123.908	mg	960728	476569
				supplier	alloy	Iron (Fe)	7439-89-6		2.986	mg	23152	11485
				supplier	alloy	Phosphorus (P)	12185-10-3		0.038	mg	295	146
				supplier	alloy	Zinc (Zn)	7440-66-6		0.153	mg	1186	588
				supplier	metallization	Nickel (Ni)	7440-02-0		1.831	mg	14197	7042
				supplier	metallization	Palladium (Pd)	7440-05-3		0.039	mg	302	150
				supplier	metallization	Gold (Au)	7440-57-5		0.018	mg	140	69
Die attach	Other Organic Materials	4.290	mg	supplier	glue	Silver(Ag)	7440-22-4		3.604	mg	840093	13862
				supplier	glue	Resin	9003-36-5		0.686	mg	159907	2638
Bonding wires	Precious metals	2.186	mg	supplier	wire	Gold (Au)	7440-57-5		2.186	mg	1000000	8408
Encapsulation	Other Organic Materials	95.250	mg	supplier	mold compound	Epoxy resin	Proprietary		8.572	mg	89996	32969
				supplier	mold compound	Silica fused (SiO2)	60676-86-0		80.011	mg	840010	307735
				supplier	mold compound	Phenol resin	205830-20-2		6.191	mg	64997	23812
				supplier	mold compound	Carbon Black	1333-86-4		0.476	mg	4997	1831
connections coating	Solder	4.432	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.432	mg	1000000	17046